



Electronic Components, Assemblies & Materials Association

**AGENDA
P-1 Committee on Resistive Devices
April 2004**

Tampa, Florida

- 1.0 Introductions
- 2.0 Committee Organizations and Procedures
 - 2.1 Membership
 - 2.2 Approval of Agenda
 - 2.3 Approval of October 2003 Meeting Minutes
 - 2.4 Correspondence
 - 2.5 Review of Committee's Scope – “ All types of resistive components regardless of technology. Includes composition, film, wirewound, thermistors, attenuators, networks, and chip resistors and exclude Integrated Passive Devices.”
 - 2.6 DSCC Report
- 3.0 Old Business
 - 3.1 Follow up of the proposed changes for ESD tests in EIA/IS-703 – Brian Piscitelli and Ed Mikoski
 - 3.1.1 Requested PN number and sent electronic version to Ed for updating of the 0.25% to “Per Users Spec.”
 - 3.2 Review Comments from the ballots of both EIA-576-A, EIA-575-A

- 3.3 Review and addition of Resistor outlines to the newly formatted/web-based PDP-100
- 3.4 Review proposed changes to EIA-886 and EIA-887 – Ted Coler
- 3.5 Start the process of generating a thin film on ceramic resistor array spec.
- 3.6 Review open P-1 projects
- 3.7 Pb-free Updates
- 3.8 Other
- 4.0 New Business
 - 4.1 Other
- 5.0 Next Meeting
- 6.0 Adjournment